NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: ZERODUR EXPANSION CLASS 1. ALTERNATE MATERIAL MAY BE USED WITH PRIOR APPROVAL FROM TMT. MATERIAL CERTIFICATIONS SHALL BE SUPPLIED.

2. BREAK SHARP EDGES TO 0.2mm TO 0.5mm EXCEPT EDGES AROUND FEET (DATUM-A) TO MAXIMUM OF 0.1mm.

3. SURFACE FINISH POLISHED TO 65/40 SCRATCH/DIG PER MIL-PRF-13830B. OPPOSITE SURFACE MAY ALSO BE FINISHED TO SAME, BUT NOT REQUIRED.

4. EDGE CHIPS LARGER THAN 0.25mm NOT PERMITTED. PERMISSIBLE EDGE CHIPS, 0.25mm OR SMALLER, MUST BE STONED OR GROUND AND THEN ETCHED. NO EDGE CHIPS PERMITTED ON DATUM-A.

5. CROSSHAIRS TO BE LASER ETCHED. TMT SHALL APPROVE ALTERNATE FABRICATION METHODS.

6. MARK UNIQUE SERIAL NUMBER: "D-67[XXXX]"; AND MANUFACTURING LOT NUMBER IN 3mm HIGH MIN. LETTERING WHERE SHOWN. LASER ETCH CHARACTERS OR OBTAIN TMT APPROVAL FOR ALTERNATE MARKING METHOD.

7. THE BOTTOM SURFACE OF THE FEET SHALL BE FINELY GROUND TO MINIMIZE SUBSURFACE DAMAGE. GRINDING SHALL BE DONE IN STEPS USING PROGRESSIVELY SMALLER ABRASIVE GRAINS. EACH GRINDING STEP SHALL REMOVE MATERIAL TO A DEPTH OF AT LEAST 1.5X THE MAXIMUM GRAIN SIZE OF THE PREVIOUS GRINDING STEP. THE FINAL GRINDING STEP SHALL USE AN ABRASIVE GRAIN SIZE OF 320 Grit.
NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: ZERODUR EXPANSION CLASS 1. ALTERNATE MATERIAL MAY BE USED WITH PRIOR APPROVAL FROM TMT. MATERIAL CERTIFICATIONS SHALL BE SUPPLIED.

2. BREAK SHARP EDGES TO 0.2mm TO 0.5mm EXCEPT EDGES AROUND FEET (DATUM-A) TO MAXIMUM OF 0.1mm.

3. SURFACE FINISH POLISHED TO 60/40 SCRATCH/DIG PER MIL-PRF-13830B. OPPOSITE SURFACE MAY ALSO BE FINISHED TO SAME, BUT NOT REQUIRED.

4. EDGE CHIPS LARGER THAN 0.25mm NOT PERMITTED. PERMISSIBLE EDGE CHIPS, 0.25mm OR SMALLER, MUST BE STONED OR GROUND AND THEN ETCHED. NO EDGE CHIPS PERMITTED ON DATUM-A.

5. CROSSHAIRS TO BE LASER ETCHED. TMT SHALL APPROVE ALTERNATE FABRICATION METHODS.

6. MARK UNIQUE SERIAL NUMBER: “S-67[XXXX]”; AND MANUFACTURING LOT NUMBER IN 3mm HIGH MIN. LETTERING WHERE SHOWN. LASER ETCH CHARACTERS OR OBTAIN TMT APPROVAL FOR ALTERNATE MARKING METHOD.

7. THE BOTTOM SURFACE OF THE FEET SHALL BE FINELY GROUND TO MINIMIZE SUBSURFACE DAMAGE. GRINDING SHALL BE DONE IN STEPS USING PROGRESSIVELY SMALLER ABRASIVE GRAINS. EACH GRINDING STEP SHALL REMOVE MATERIAL TO A DEPTH OF AT LEAST 1.5X THE MAXIMUM GRAIN SIZE OF THE PREVIOUS GRINDING STEP. THE FINAL GRINDING STEP SHALL USE AN ABRASIVE GRAIN SIZE OF 320 Grit.

DIMENSIONS ARE IN MILLIMETERS

SURFACE FINISH PER ASME 14.36-1996

UNLESS OTHERWISE SPECIFIED

THIRD ANGLE PROJECTION
DO NOT SCALE DRAWING
INTERPRET DRAWING PER ASME Y14.5M

METHOD OF PRODUCTION: LASER ETCHED
NOTES: UNLESS OTHERWISE SPECIFIED.
1. GOLD COATING SHALL BE APPLIED TO ALL SURFACES EXCEPT AS INDICATED IN NOTE 6 & 7. COATING THICKNESS SHALL BE 0.50 MICRONS. GOLD SHALL BE 99.99% PURE OR BETTER OVER 0.05 MICRONS CHROMIUM. MATERIAL CERTIFICATION SHALL BE SUPPLIED.

COUNTERSINK FEATURES ON FRONT AND BACK FACES SHALL BE COMPLETELY COATED.

3. SUBSTRATE TEMPERATURE MAY NOT ExCEED 130°C DURING COATING OR PROCESSING.

COATING THICKNESS ON FRONT AND BACK FACES (50 X 62 mm) SHALL BE 0.45 TO 0.55 MICRONS (± 10% TOL).

INDICATED AREAS MUST BE COATED BUT ELECTRICALLY ISOLATED FROM ALL OTHER SURFACES. ELECTRICAL RESISTANCE SHALL EXCEED 20 MEGOHMS. ALL OTHER COATED SURFACES SHALL BE ELECTRICALLY CONTIGUOUS.

THE FOLLOWING SURFACES SHALL NOT BE COATED: BOTTOMS OF THE THREE FEET IDENTIFIED AS DATUM-A. A SUFFICIENT LENGTH OF THE 2.0 THROUGH HOLE AS REQUIRED TO ELECTRICALLY ISOLATE THE ZONE DEFINED BY NOTE 5 FROM OTHER COATED SURFACES. THE 4.0 VERTICAL COATING THE TOP AND BOTTOM COUNTERBORE IS OPTIONAL.

8. UNLESS OTHERWISE SPECIFIED COATING THICKNESS ON ALL REMAINING SURFACES SHALL BE 0.25 TO 1.00 MICRONS (-50% TO +100% OF NOMINAL).
NOTES: UNLESS OTHERWISE SPECIFIED.

1. GOLD COATING SHALL BE APPLIED TO ALL SURFACES EXCEPT AS INDICATED IN NOTE 6 & 7. COATING THICKNESS SHALL BE 0.50 MICRONS. GOLD SHALL BE 99.99% PURE OR BETTER OVER 0.05 MICRONS CHROMIUM. MATERIAL CERTIFICATION SHALL BE SUPPLIED.

2. COUNTERSINK FEATURES ON FRONT AND BACK FACES SHALL BE COMPLETELY COATED.

3. SUBSTRATE TEMPERATURE MAY NOT EXCEED 130°C DURING COATING OR PROCESSING.

4. COATING THICKNESS ON FRONT AND BACK FACES (50 X 62 mm) SHALL BE 0.45 TO 0.55 MICRONS (±10% TOL).

5. INDICATED AREAS MUST BE COATED BUT ELECTRICALLY ISOLATED FROM ALL OTHER SURFACES. ELECTRICAL RESISTANCE SHALL EXCEED 20 MEGOHMS. ALL OTHER COATED SURFACES SHALL BE ELECTRICALLY CONTIGUOUS.

6. THE FOLLOWING SURFACES SHALL NOT BE COATED: BOTTOMS OF THE THREE FEET IDENTIFIED AS DATUM-A. A SUFFICIENT LENGTH OF THE 2.0 THROUGH HOLE AS REQUIRED TO ELECTRICALLY ISOLATE THE ZONE DEFINED BY NOTE 5 FROM OTHER COATED SURFACES. THE 4.0 VERTICAL.

7. COATING THE TOP AND BOTTOM COUNTERBORE IS OPTIONAL.

8. UNLESS OTHERWISE SPECIFIED COATING THICKNESS ON ALL REMAINING SURFACES SHALL BE 0.25 TO 1.00 MICRONS (-50% TO +100% OF NOMINAL).

COATING DIMENSIONS - SENSE PADDLE

THIRD ANGLE PROJECTION

COATING DIMS - 67
TMT.CTR.DWG.11.011.DRF06

TMT Observatory Corporation
www.tmt.org
NOTES: UNLESS OTHERWISE SPECIFIED.

1. USE ONLY .999 PURE OR BETTER INDIUM SOLDER.
2. SUBSTRATE TEMPERATURE MAY NOT EXCEED 150°C DURING PROCESSING.
3. CABLE AND CONNECTOR NOT SHOWN TO SCALE.